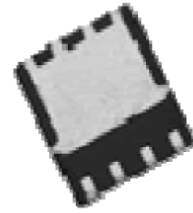


## GENERAL DESCRIPTION

The MS40N06 is the highest performance trench N-ch MOSFETs with extreme high cell density , which provide excellent R<sub>DS(on)</sub> and gate charge for most of the synchronous buck converter applications .

The QM6006M6 meet the RoHS and Green Product requirement , 100% EAS guaranteed with full function reliability approved.



**RoHS**  
COMPLIANT

HALOGEN  
**FREE**  
Available

## FEATURES

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

Symbol	Parameter	Rating		Units
V <sub>DS</sub>	Drain-Source Voltage	60		V
V <sub>GS</sub>	Gate-Source Voltage	±20		V
I <sub>D@TC=25°C</sub>	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	40		A
I <sub>D@TC=100°C</sub>	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	25		A
I <sub>D@TA=25°C</sub>	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	7.4		A
I <sub>D@TA=70°C</sub>	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	6		A
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	80		A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	67		m J
I <sub>AS</sub>	Avalanche Current	28		A
P <sub>D@TC=25°C</sub>	Total Power Dissipation <sup>4</sup>	59		W
P <sub>D@TA=25°C</sub>	Total Power Dissipation <sup>4</sup>	2		W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150		°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150		°C
Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction-Ambient <sup>1</sup>	---	62	°C/W
R <sub>θJC</sub>	Thermal Resistance Junction-Case <sup>1</sup>	---	2.1	°C/W

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	VGS=0V , ID=250uA	60	---	---	V
$\Delta$ BVDSS/ $\Delta$ TJ	BVDSS Temperature Coefficient	Reference to 25°C, ID=1mA	---	0.057	---	V/°C
RDS(ON)	Static Drain-Source On-Resistance <sup>2</sup>	VGS=10V , ID=30A	---	14	18	mΩ
		VGS=4.5V , ID=15A	---	16	20	
VGS(th)	Gate Threshold Voltage	VGS=VDS , ID =250uA	1.2	---	2.5	V
$\Delta$ VGS(th)	VGS(th) Temperature Coefficient		---	-5.68	---	mV/°C
IDSS	Drain-Source Leakage Current	VDS=48V , VGS=0V , TJ=25°C	---	---	1	uA
		VDS=48V , VGS=0V , TJ=55°C	---	---	5	
IGSS	Gate-Source Leakage Current	VGS=±20V , VDS=0V	---	---	±100	nA
gfs	Forward Transconductance	VDS=5V , ID=30A	---	35.2	---	S
Rg	Gate Resistance	VDS=0V , VGS=0V , f=1MHz	---	1.7	3.4	Ω
Qg	Total Gate Charge (4.5V)	VDS=48V , VGS=4.5V , ID=15A	---	19.3	27	nC
Qgs	Gate-Source Charge		---	7.1	10	
Qgd	Gate-Drain Charge		---	7.6	10.6	
Td(on)	Turn-On Delay Time	VDD=30V , VGS=10V , RG=3.3Ω, ID=15A	---	7.2	14.4	ns
Tr	Rise Time		---	50	90	
Td(off)	Turn-Off Delay Time		---	36.4	73	
Tf	Fall Time		---	7.6	15.2	
Ciss	Input Capacitance	VDS=15V , VGS=0V , f=1MHz	---	2423	3392	pF
Coss	Output Capacitance		---	145	203	
Crss	Reverse Transfer Capacitance		---	97	136	
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
EAS	Single Pulse Avalanche Energy <sup>5</sup>	VDD=25V , L=0.1mH , IAS=15A	19	---	---	mJ
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit



# MS40N06 60V N-Channel MOSFET

IS	Continuous Source Current <sup>1,6</sup>	VG=VD=0V , Force Current	---	---	40	A
ISM	Pulsed Source Current <sup>2,6</sup>		---	---	80	A
VSD	Diode Forward Voltage <sup>2</sup>	VGS=0V , IS=A , TJ=25°C	---	---	1	V
trr	Reverse Recovery Time	IF=15A , dI/dt=100A/μs , TJ=25°C	---	16.3	---	nS
Qrr	Reverse Recovery Charge		---	11	---	nC

Note :

1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
2. The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
3. The EAS data shows Max. rating . The test condition is VDD=25V,VGS=10V,L=0.1mH,IAS=28A
4. The power dissipation is limited by 150°C junction temperature
5. The Min. value is 100% EAS tested guarantee.
6. The data is theoretically the same as ID and IDM , in real applications , should be limited by total power dissipation.

- Characteristic Curves

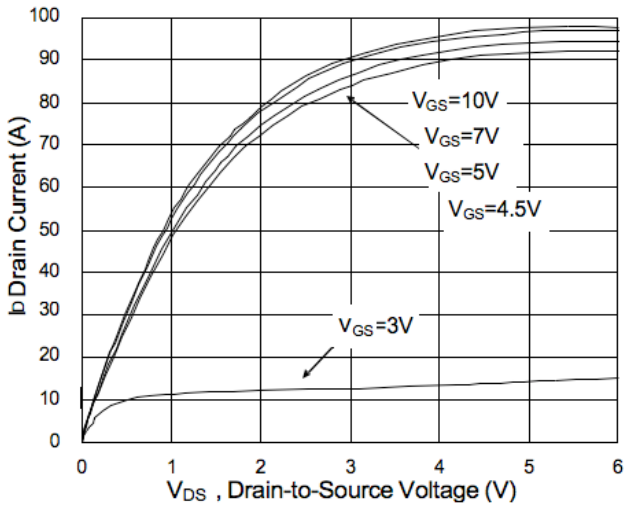


Figure 1. Typical Output Characteristics

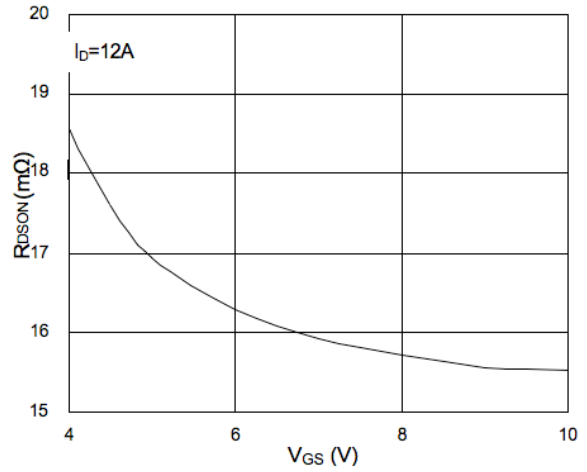


Figure 2. On-Resistance v.s Gate-Source

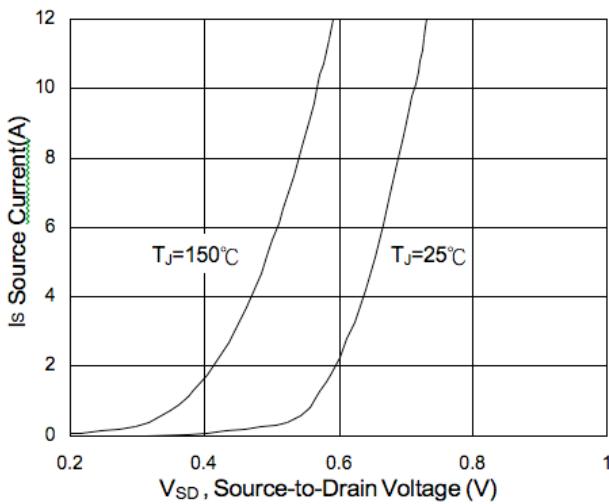


Figure 3. Forward Characteristics of Reverse

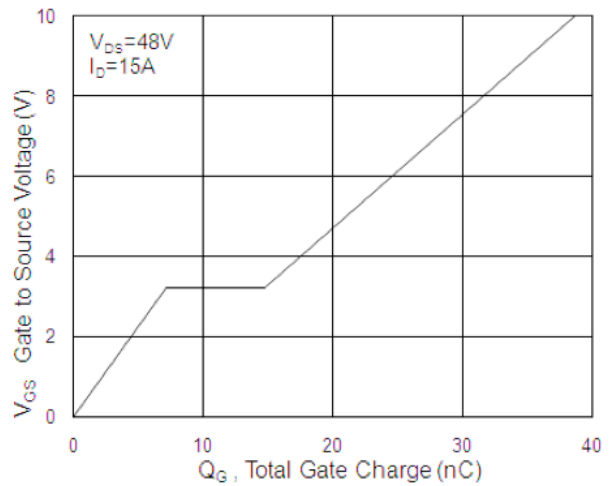


Figure 4. Gate-Charge Characteristics

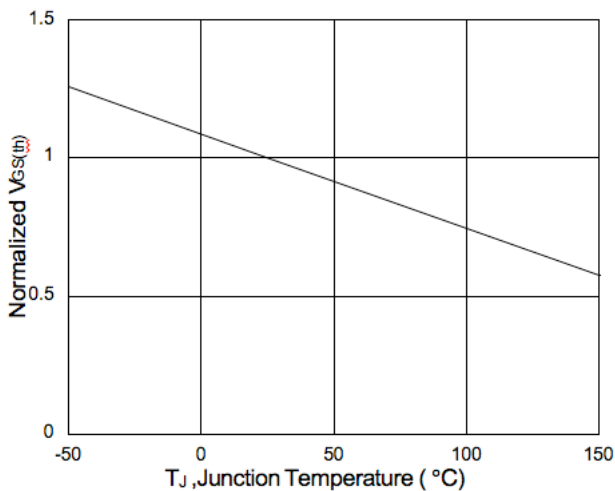


Figure 5. Normalized  $V_{GS(th)}$  v.s  $T_J$

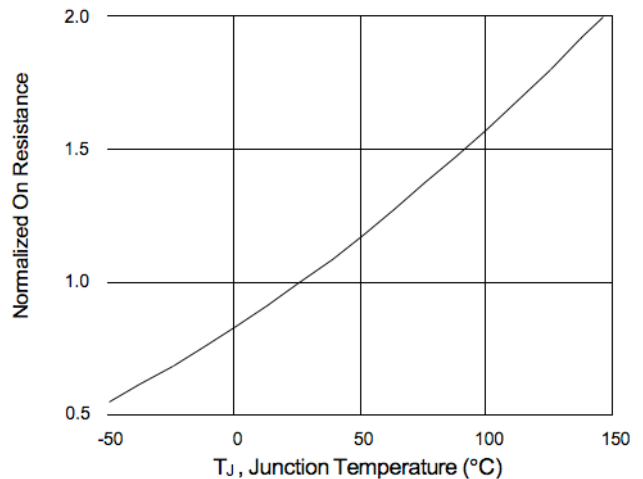


Figure 6. Normalized  $R_{DS(on)}$  v.s  $T_J$

- Characteristic Curves

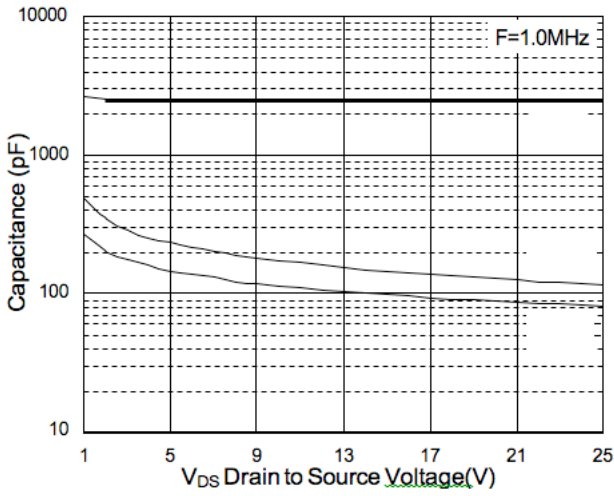


Figure 7. Capacitance

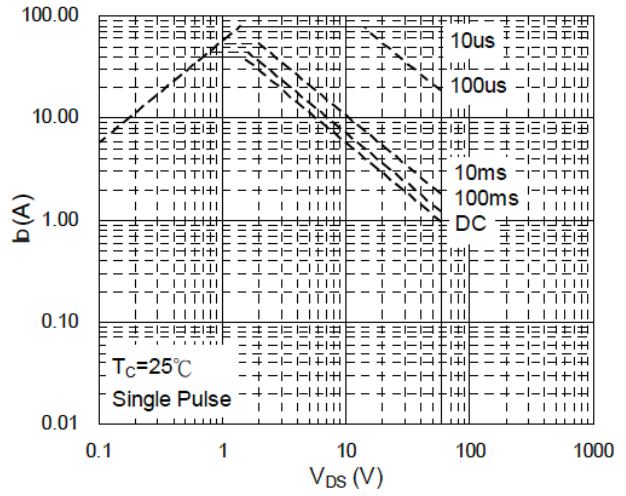


Figure 8. Safe Operating Area

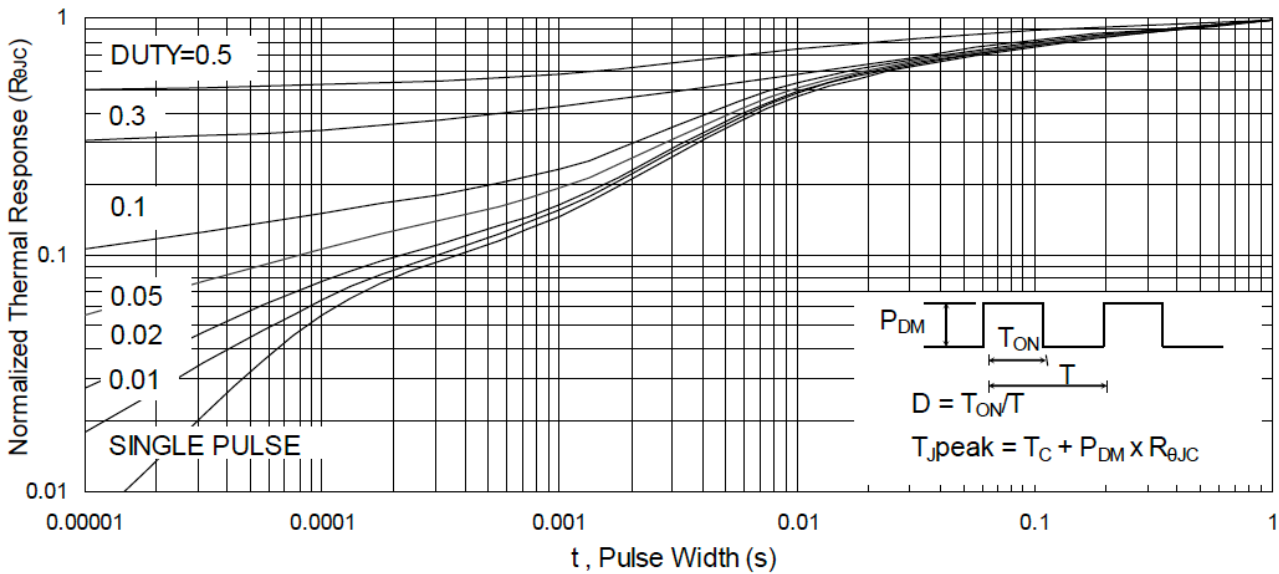


Figure 9. Normalized Maximum Transient Thermal Impedance

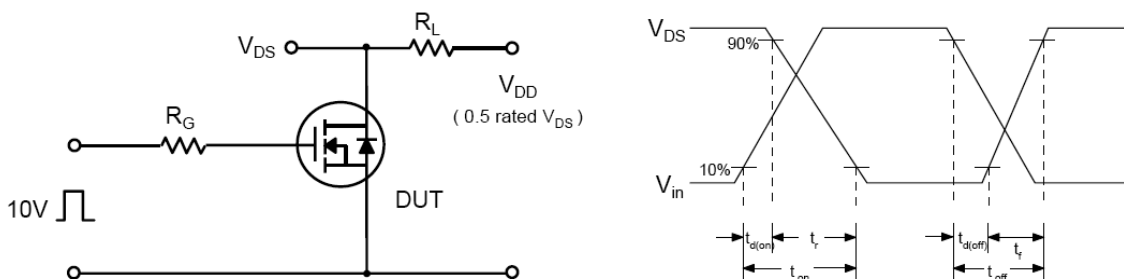
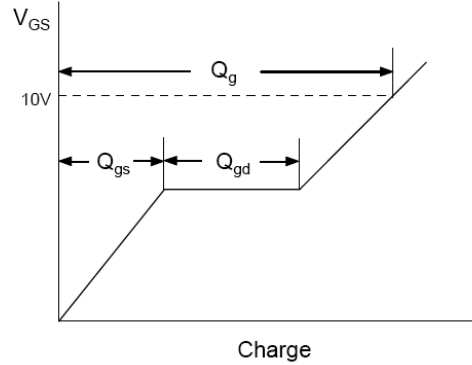
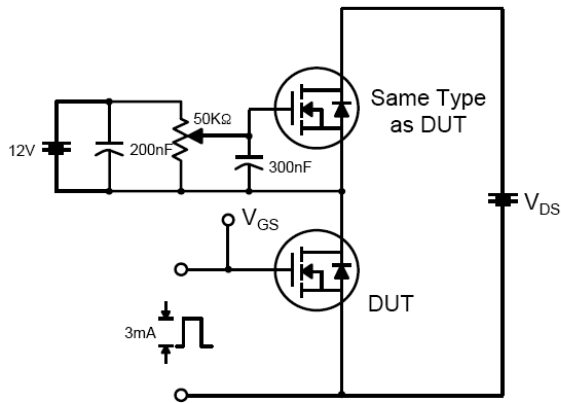
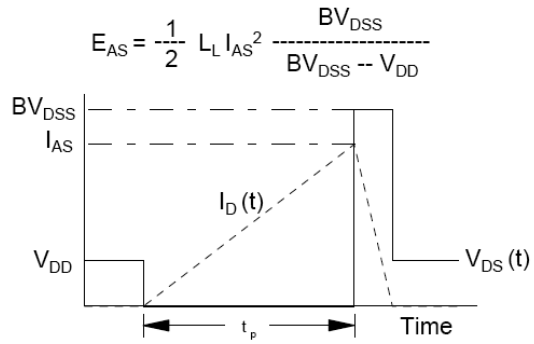
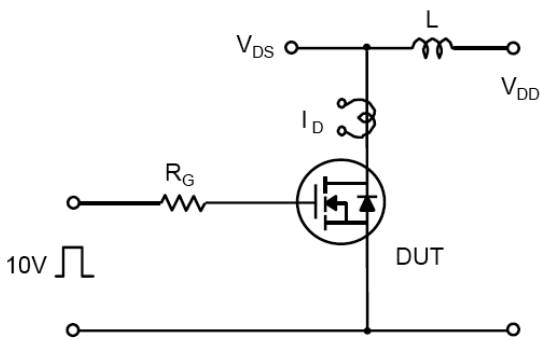


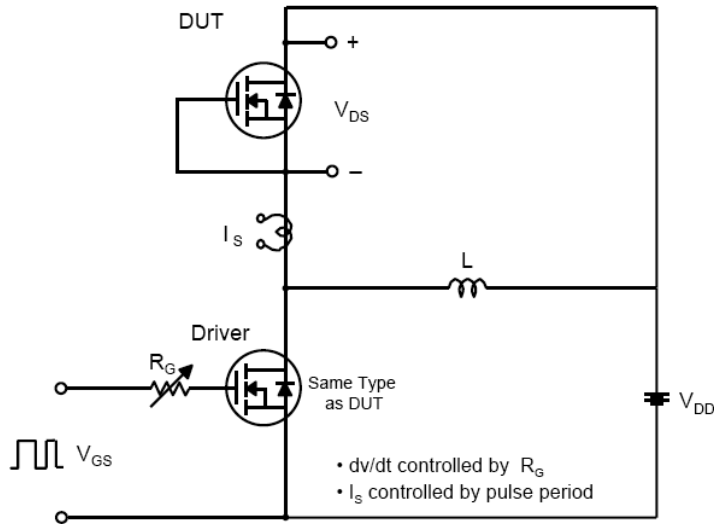
Fig 10. Resistive Switching Test Circuit & Waveforms

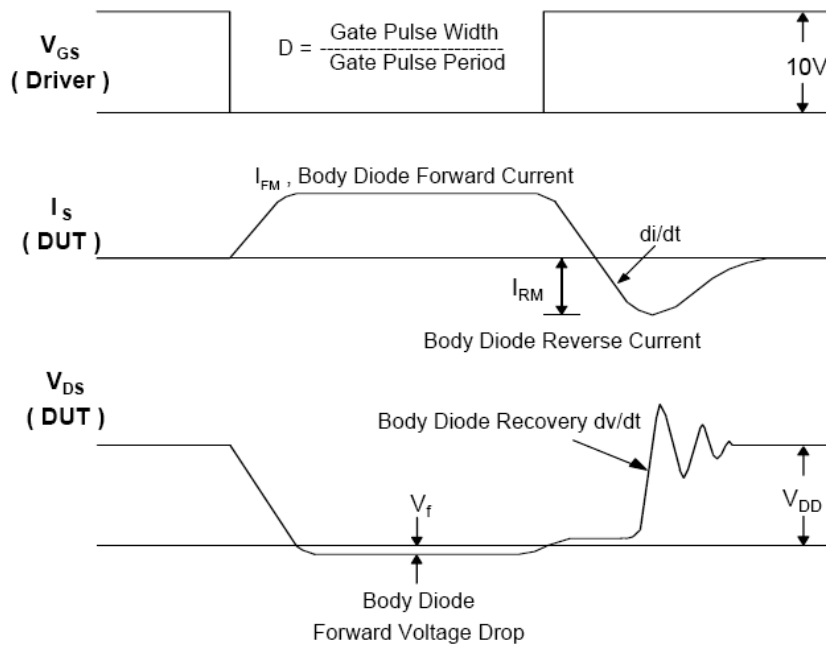


**Fig 11. Gate Charge Test Circuit & Waveform**



**Fig 12. Unclamped Inductive Switching Test Circuit & Waveforms**





**Fig 131. Peak Diode Recovery  $dv/dt$  Test Circuit & Waveforms**



# MS40N06 60V N-Channel MOSFET

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